



REACTIVE NANO-FILMS OF AL AND PT

8TH World Congress on Computational Mechanics (WCCM8)

**5th European Congress on Computational Methods in Applied
Sciences and Engineering (ECCOMAS 2008)**

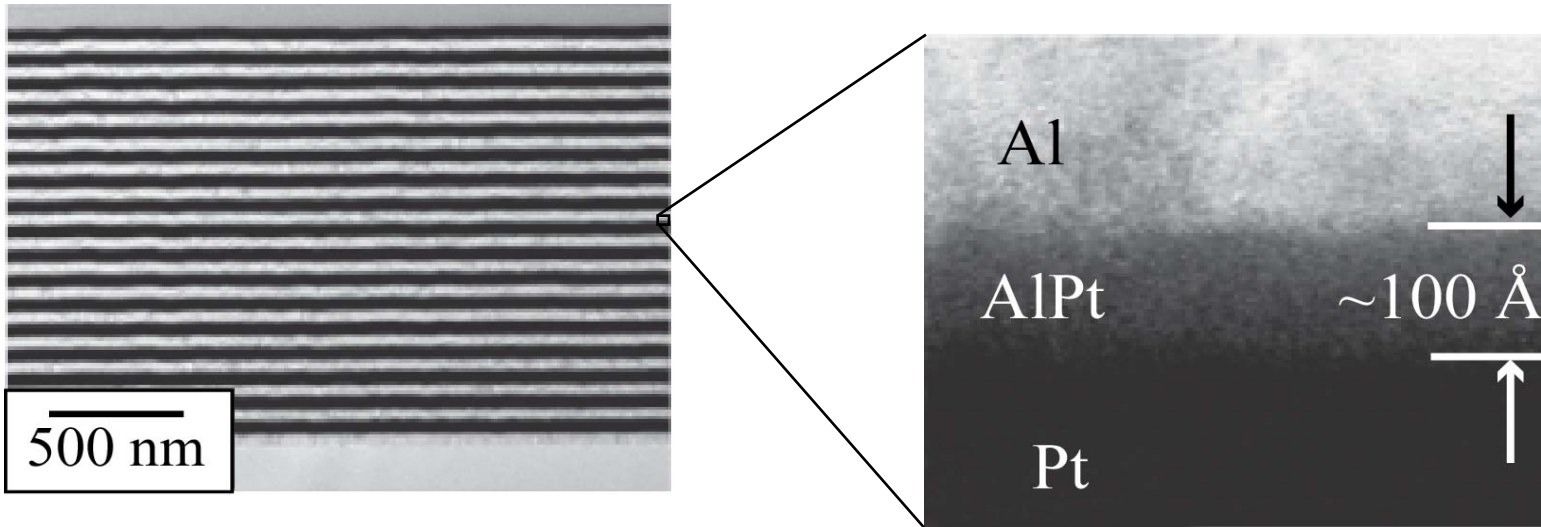
June 30-July 5, 2008

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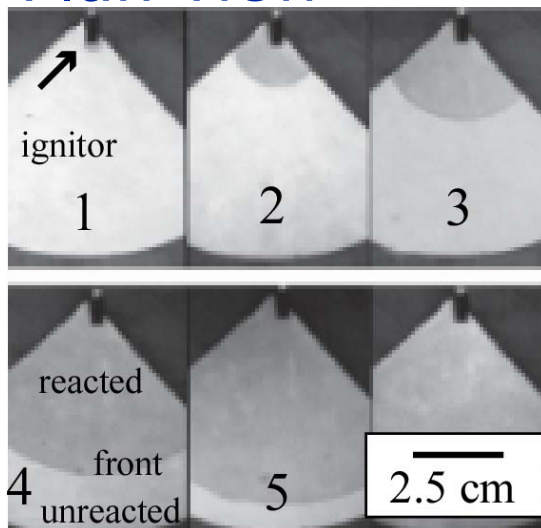
Soldering or Brazing of Microelectronics

(Rapid, localized heating minimizes damage)

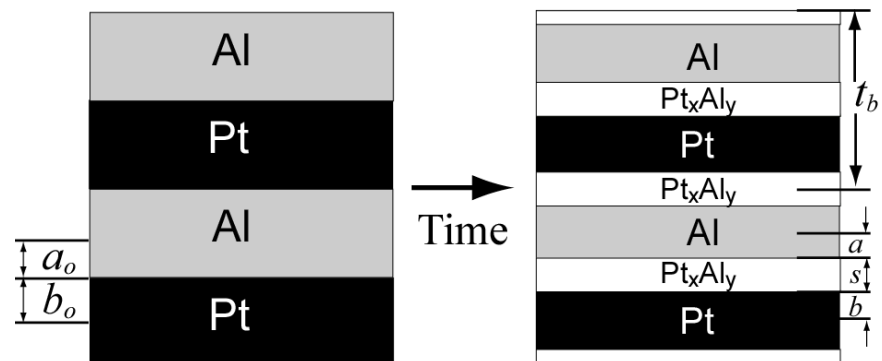
Cross section



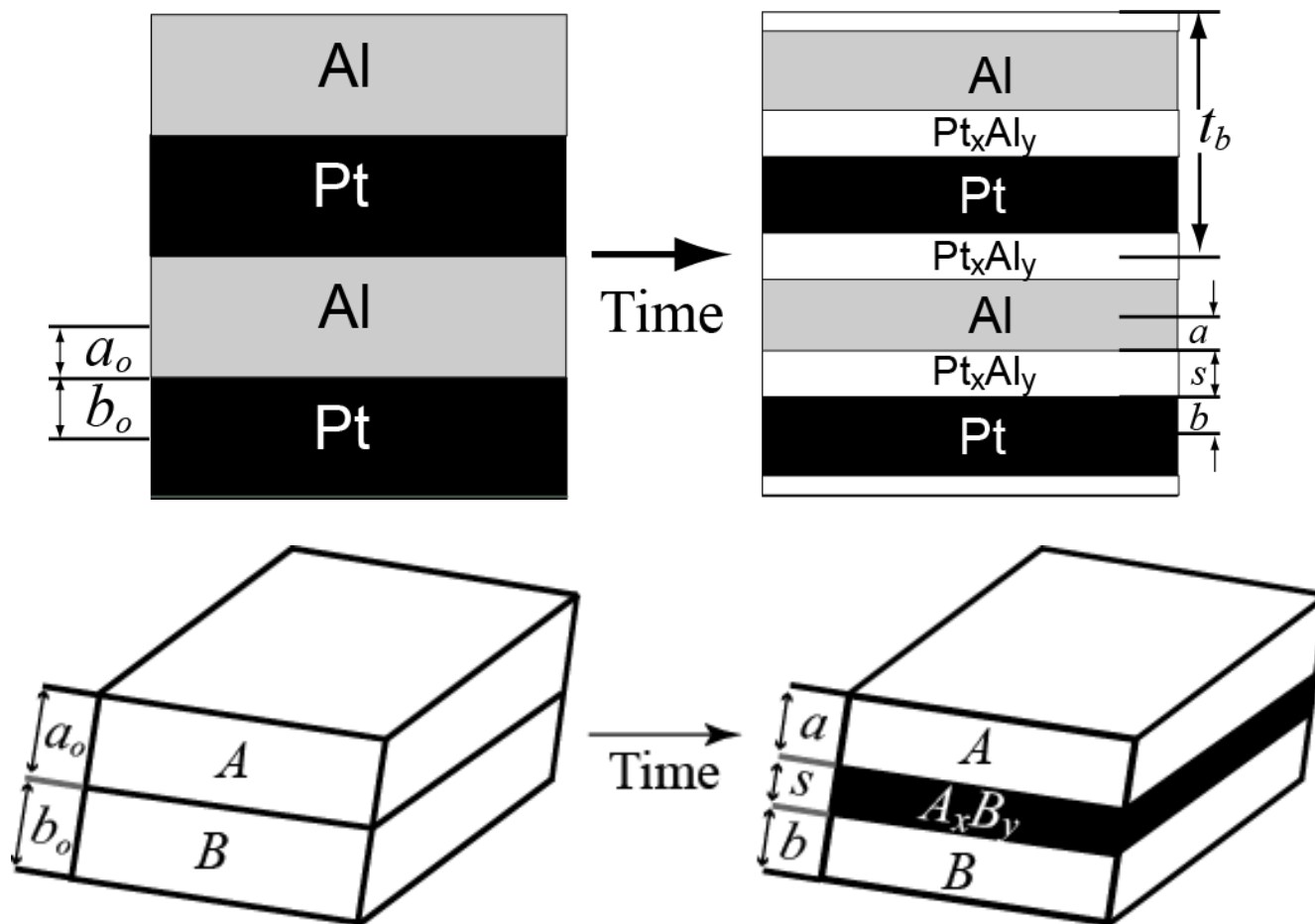
Plan view



Schematic

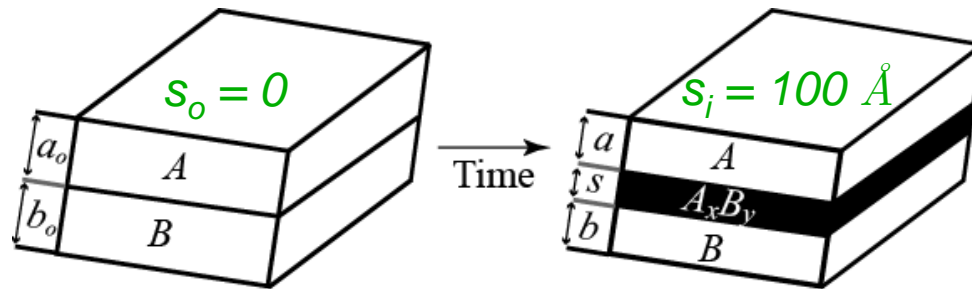


Two bilayers of Al and Pt



$$t_b = 2(a + b + s)$$

1D diffusion controlled growth reaction with zero strain assumption*



ODE's

$$\frac{da}{dt} = -\frac{D}{s}$$

$$\frac{db}{dt} = -\frac{b_o}{a_o} \frac{D}{s}$$

$$\frac{ds}{dt} = -\frac{D}{s} \left(1 + \frac{b_o}{a_o} \right)$$

$$\frac{dF}{dt} = -\frac{D}{a_o s}$$

Auxiliary Eqns.

$$D = D_o \exp\left(-\frac{E}{RT}\right)$$

$$a = \frac{a_o + b_o - s}{1 - \frac{\rho_A}{\rho_B} \frac{M_B}{M_A} \frac{\xi_B}{\xi_A}}$$

$$b = a \frac{\rho_A}{\rho_B} \frac{M_B}{M_A} \frac{\xi_B}{\xi_A}$$

$$\rho_{AB} = \frac{a_o \rho_A + b_o \rho_B}{a_o + b_o}$$

Algorithm

Choose a_o , calculate b_o

Choose s_i , calculate a_i , b_i , and F_i

Solve ODE's for s and F

Energy Equation

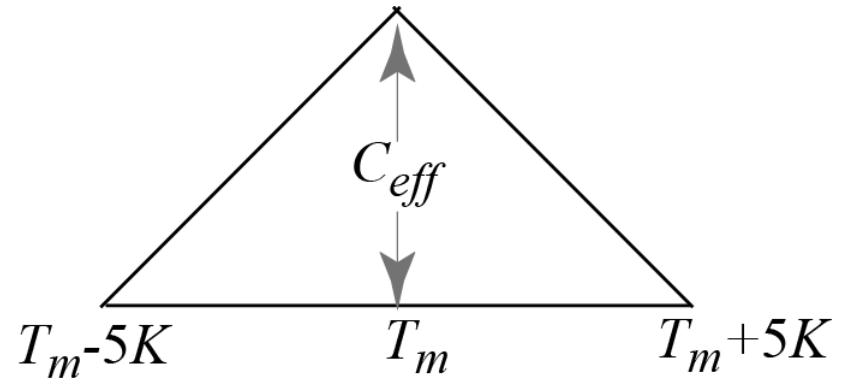
$$\rho c \frac{\partial T}{\partial t} \nabla \cdot (k \nabla T) = -Q \rho \frac{dF}{dt}$$

*Hardt AP and Phung PV, "Propagation of gasless reactions in solids—I. Analytical study of exothermic intermetallic reaction rates," *Combustion and Flame*, **21**, pp. 77-89, 1973.

Parameters

Thermophysical Properties

| Property | Description | Al | Pt | AlPt |
|--------------------------------|------------------------|---------------------|---------------------|---------------------|
| c , J/kgK | Specific Heat | 894-900 | 133 | 226 |
| c_{eff} , J/kgK | Effective c at T_m | $h_{fus}/^{\circ}T$ | $h_{fus}/^{\circ}T$ | $h_{fus}/^{\circ}T$ |
| $^{\circ}T$, K | half of mush zone | 4-6 | 4-6 | 4-6 |
| h_f , J/kg | Formation enthalpy | 0 | 0 | -901,000 |
| h_{fus} , J/kg ^b | Latent enthalpy | 397,000 | 114,000 | 48,300; 100,000 |
| k , W/mK | Thermal conductivity | 213-261 | 71.6 | 158 |
| M_w , kg/kgmol | Molecular weight | 27.0 | 195 | 222 |
| $^{\circ}$, kg/m ³ | Density | 2700 | 21500 | 11600 |
| T_m , K | Melting point | 934 | 2040 | 934, 2040 |



$$Area = \frac{1}{2}(Base \times Height)$$

$$h_{fus} = \frac{1}{2}(10\text{ K} \times C_{T_{mp}})$$

$$C_{T_{mp}} = 5 \times h_{fus}$$

Diffusion model parameters

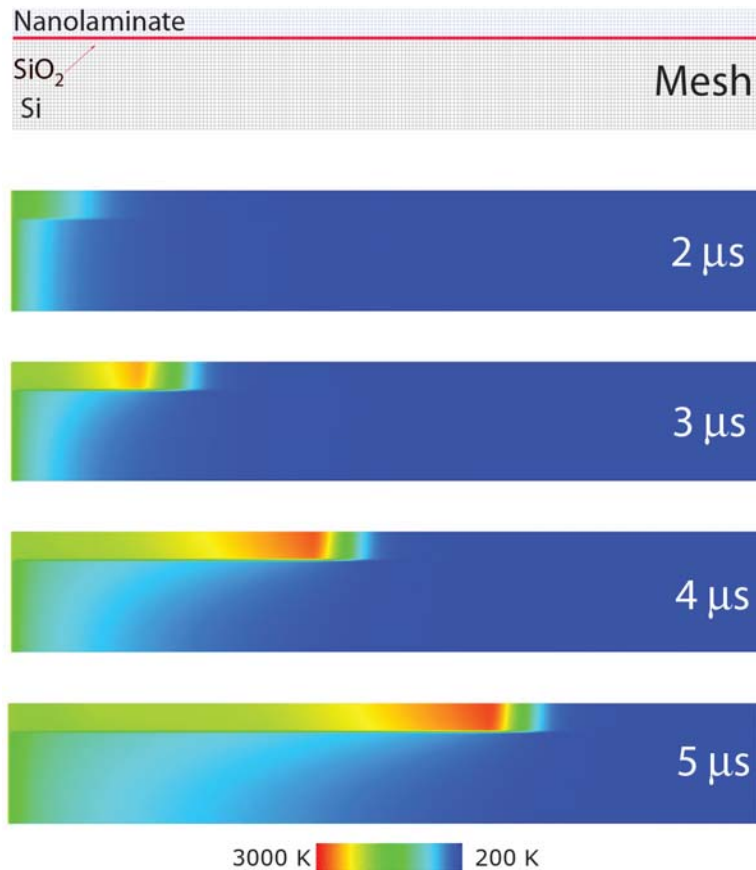
| Property | Description | AlPt |
|---------------------------|------------------------------------|----------------------|
| s_o , m | Initial thickness of reacted layer | 1×10^{-8} |
| D_o , m ² /s | Initial diffusion coefficient | 1×10^{-7} |
| E , J/kgmol | Activation energy | 4.1868×10^7 |

Two Phase Changes (Al, Pt)*

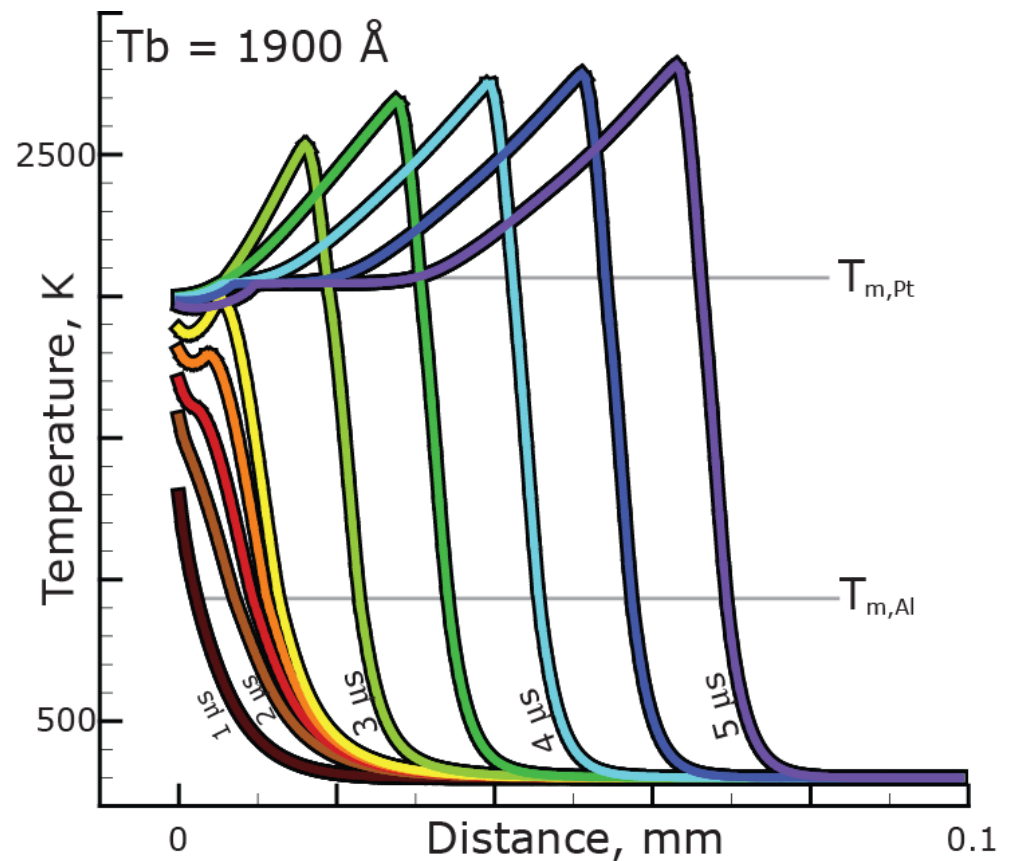
*Effective capacitance method: Yao, L.S. and Prusa, J., Melting and freezing, *Advances in Heat Transfer*, 5th Edition, John Wiley & Sons, New York, 2002.

Temperature profiles leading to ignition

2D Axisymmetric Temperature

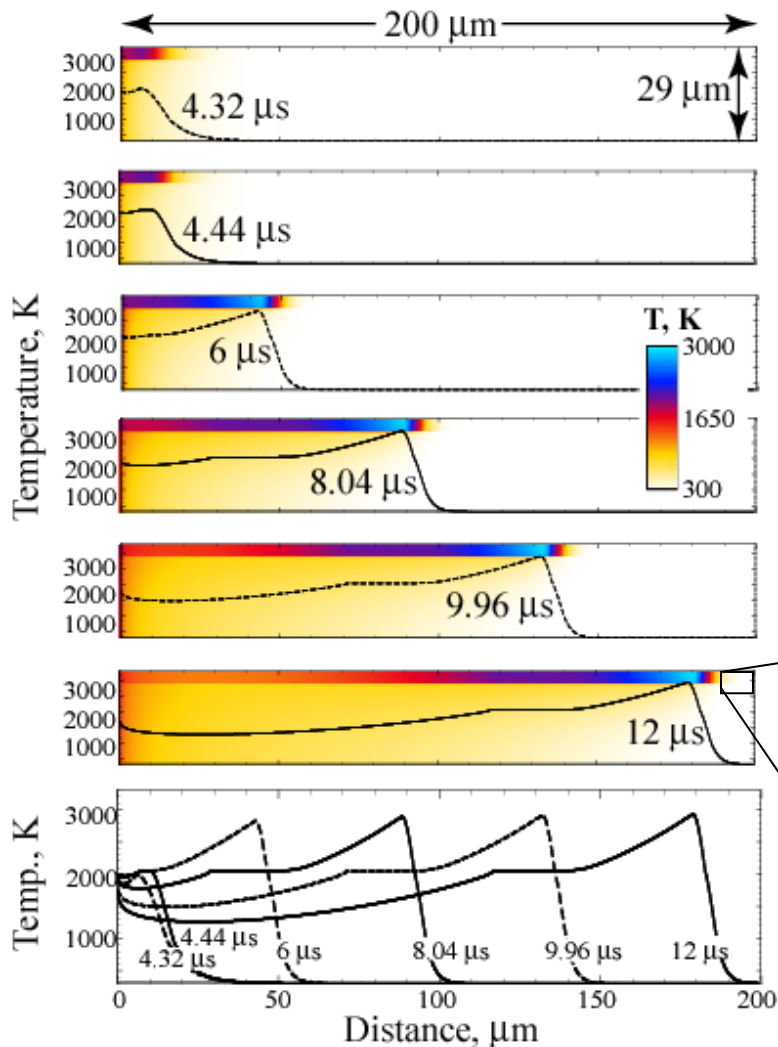


Temperature on top of nanolaminate

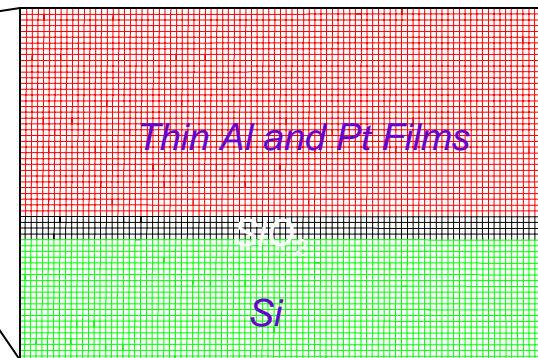


Reaction energy sufficient to melt both layers

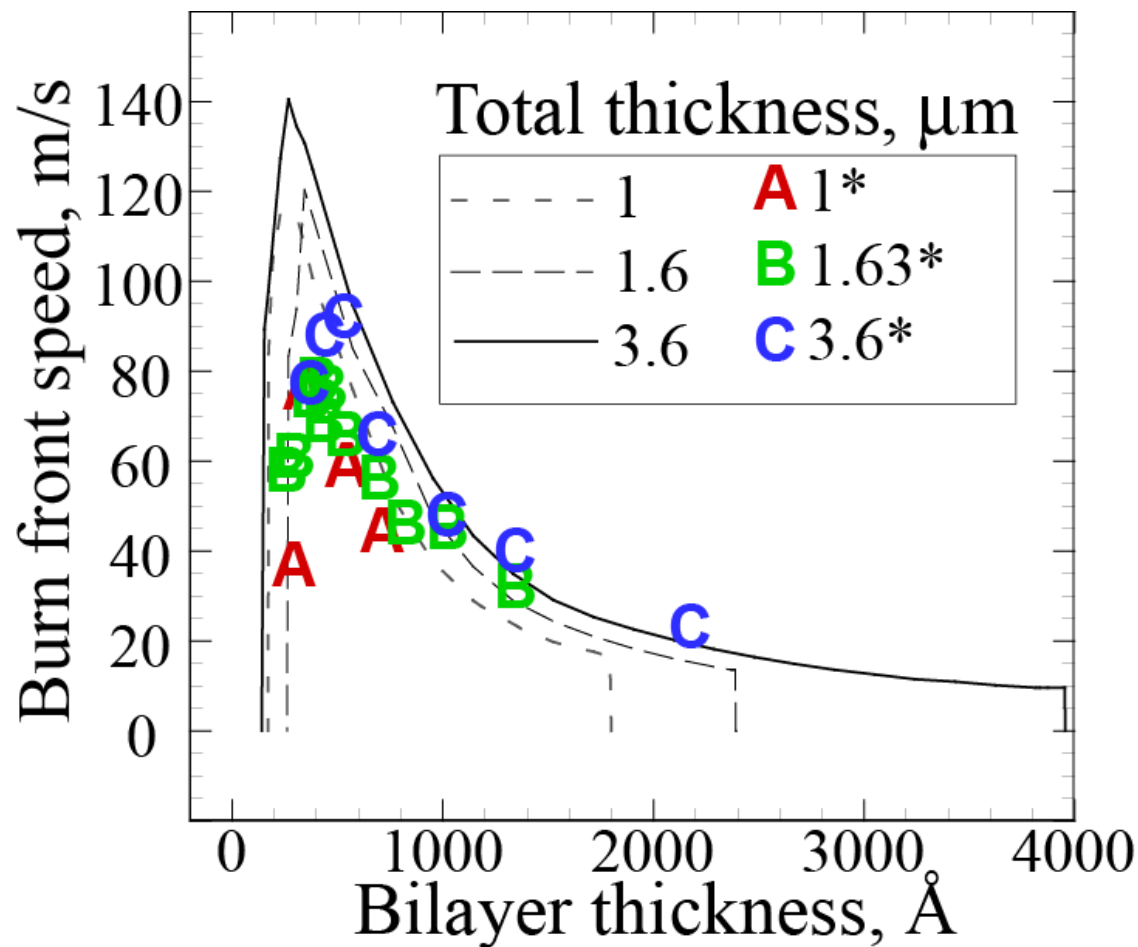
2D axisymmetric mesh (580,000 elements)



- Elements are $0.1 \times 0.1 \mu\text{m}$
- Fixed time step, $4 \times 10^{-10} \text{ s}$
- Ignition occurs $\sim 10 \mu\text{m}$ from electric match
- Al melt in front of wave
- Solidification of AlPt should occur at 1830 K



Front Velocity Variations with Bilayer Thickness



*Adams DP, Rodriguez MA, Tigges CP, and Kotula PG, "Self-propagating, high-temperature combustion synthesis of rhombohedral AlPt thin films," *J. Mater. Res.*, Vol. **21**(12), pp. 3168-3179 (2006).



Summary and Conclusions

- The diffusion-limited model of Hardt and Phung has been used with a simple phase-change model to simulate the self-sustained, high temperature front propagation of Al/Pt nanolaminates on silicon substrates using a 2D axisymmetric finite element code.
- Results were within experimental uncertainty for nanolaminate thicknesses ranging from 1 to 3.6 μm
- Despite success, deficiencies should be addressed
 - Temperature dependent thermophysical properties
 - Solidification of mixed material
 - Strain due to thermal expansion
 - Adaptive mesh refinement
 - Stiff numerics